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INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

Docket: 245-53153

App: 09/369,679

Applicant: Paul et al.

Filed: August 5,
1999

Art Unit: 3726

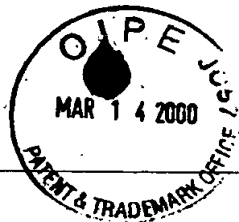
U.S. PATENT DOCUMENTS

Init. *		Number	Date	Name	Class	Sub	Filed
<i>Av</i>	AA	4,875,619	10/1989	Anderson et al.	228	190	
	AB	5,610,645	3/1997	Moore et al.	347	93	
	AC	5,087,930	2/1992	Roy et al.	346	140	
	AD	5,611,214	3/1997	Wegeng et al.	62	498	
	AE	5,689,966	11/1997	Zess et al.	62	238.6	
<i>Av</i>	AF	5,811,062	9/1998	Wegeng et al.	422	129	

OTHER DOCUMENTS

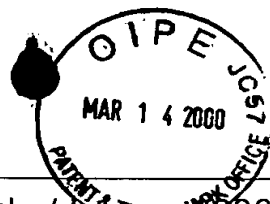
<i>Av</i>		A	Goldberg, (March 1984) Narrow Channel Forced Air Heat Sink, IEEE Transactions on Components, Hybrids, and Manufacturing Technology, Vol. CHMT-7 No. 1, pages 154-159.
		D	Haas, et al. (1993) Fabrication and Performance of MMW and SMMW Platelet Horn Arrays, <i>Intl. J. Infrared and Millimeter Waves</i> , 14(11): 2289-93.
		E	Martin, P.M., et al. (1995) Microchannel heat exchangers for advanced climate control, Proc. SPIE, 2639: 82-8.
		F	Wegeng, R.S., et al. (December 1995) Energy systems miniaturization technologies, devices, and systems, <i>Proceedings of the International Symposium on Advanced Energy Conversion Systems and Related Technologies (RAN95)</i> .
<i>Av</i>		G	Wegeng, R.S., C.J. Call, and M.K. Drost (February 1996) Chemical system miniaturization, <i>Proceedings of the AIChE Spring National Meeting</i> .

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<p><i>See</i></p>	H	Hershberg, G., (1988) Manufacturing Technology of the Tektronix Digital Ink Jet Head, <i>SPSE3rd International Congress on Advanced in Non-Impact Printing Technologies, Journal of Imaging Technology</i> , 14:124-128 (1998).			
	I	Knight, R., (1992) Optimal Thermal Design of Air Cooled Forced Convection Finned Heat Sinks-Experimental Verification, <i>IEEE Transactions of Components...</i> , 15:754-760.			
	J	Esposito, A. (1988) Fluid Power with Applications, pages 380-381, <i>Prentice Hall</i> .			
	K	Humpston, G. and Jacobson, DM, (1993) Principles of Soldering and Brazing, 4.4.2. Diffuion Soldering and Brazing, ASM International pages 128-143.			
	L	Technology Development Through Industrial Partnerships, (October 1997) <i>Federal Energy Technology Center</i> .			
	M	Matson, Dean W., Laser micromachined microchannel solvent separator, <i>SPIE Vol. 3223</i> , pages 253-259.			
	N	Martin, P.M., et al. (1997) Microfabrication methods for michrochannel reactors and separations systems, <i>Pacific Northwest National Laboratory</i> .			
	O	Krause, V. , et al. (1994) Microchannel coolers for high power laser diodes in copper technology, <i>Proc. SPIE Vol. 2148</i> : 351-358.			
	P	Kleiner, M.B., (December 1995) High Performance Forced Air Cooling Scheme Employing Microchannel Heat Exchangers, <i>IEEE Transactions on Components, Packaging, and Manufacturing Technology</i> , Vol. 18, No. 4.			
	Q	Jacobson, DM and Humpston, G., (February 1992) Diffusion Soldering, <i>Soldering and Surface Mount Technology</i> , 10:27-32.			
	R	NASA, (1988) National Space Transportation System Shuttle Reference Manual, p. 8, located at www.ksc.nasa.gov/shuttle/technology/sts-newsref/sts-oms.html .			
	S	Ridley, N. et al., (September 1992) Isostatic diffusion bonding of microduplex stainless steel, <i>Mat.Sci. and Tech.</i> , 8:791-795.			
<p><i>See</i></p>	T	Khan, T. and Wallach, E.R., (June 1996) Transient liquid phase diffusion bonding and associated recrystallization phenomenon when joining ODS ferritic superalloys, <i>J. of Mat. Sci.</i> , 31:2937-43.			

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<i>Am</i>		U	Lopez, B. et al., (January 1996) Microstructural analysis of steel-nickel alloy clad interfaces, <u>Mat. Sci. and Tech.</u> , 12:45-55.
EXAMINER: <i>Allen W. O'G</i>			DATE <i>4/3/02</i>
*Examiner: Initial if considered, whether or not in conformance with MPEP 60; draw line through cite if not in conformance and not considered. Send copy.			

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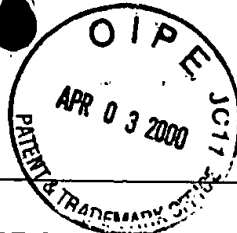
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OTHER DOCUMENTS				
<i>fw</i>			Cuta, J.M., et al., (1995) Fabrication and testing of microchannel heat exchangers, SPIE Conf., 2640:152-60.	
<i>fw</i>			Haas, R.W., (1995) Further development of MMW and SMMW platelet feed horn arrays, Astron. Soc. Pac. Conf. Ser., 75:99-105.	
EXAMINER: <i>Allen W. Olson</i>			DATE <i>4/3/02</i>	
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